



N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ)
30	0.050 at V _{GS} = 10 V	4.5	3.16 nC
	0.080 at V _{GS} = 4.5 V	3.4	

FEATURES

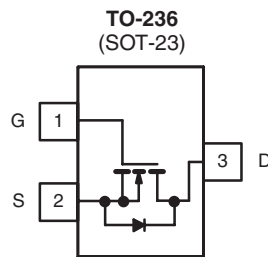
- TrenchFET[®] Power MOSFET
- PWM Optimized
- 100 % R_g tested



RoHS
COMPLIANT

APPLICATIONS

- Battery Switch
- DC/DC Converter



Top View
Si2316DS (M6)*
*Marking Code

Ordering Information: Si2316BDS-T1-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current (T _J = 150 °C)	I _D	T _C = 25 °C	4.5
		T _C = 70 °C	3.6
		T _A = 25 °C	3.9 ^{b, c}
		T _A = 70 °C	3.13 ^{b, c}
Pulsed Drain Current	I _{DM}	20	A
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	
		T _A = 25 °C	1.04 ^{b, c}
Maximum Power Dissipation	P _D	T _C = 25 °C	1.66
		T _C = 70 °C	1.06
		T _A = 25 °C	1.25 ^{b, c}
		T _A = 70 °C	0.8 ^{b, c}
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	80	100	°C/W
Maximum Junction-to-Foot (Drain)	R _{thJF}	60	75	

- Notes:
- a. Based on T_C = 25 °C.
 - b. Surface Mounted on 1" x 1" FR4 Board.
 - c. t = 5 sec.
 - d. Maximum under Steady State conditions is 130 °C/W.

MOSFET SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{DS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	30			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		23.92		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.2		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	1		3	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 30\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}$, $V_{GS} = 10\text{ V}$	20			A
Drain-Source On-State Resistance ^a	$r_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 3.9\text{ A}$		0.041	0.050	Ω
		$V_{GS} = 4.5\text{ V}$, $I_D = 3.3\text{ A}$		0.064	0.080	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}$, $I_D = 3.9\text{ A}$		6		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = 15\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$		350		μF
Output Capacitance	C_{oss}			65		
Reverse Transfer Capacitance	C_{rss}			37		
Total Gate Charge	Q_g	$V_{DS} = 15\text{ V}$, $V_{GS} = 10\text{ V}$, $I_D = 3.9\text{ A}$		6.35	9.6	nC
		$V_{DS} = 15\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 3.9\text{ A}$		3.16	4.8	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 3.9\text{ A}$		1.56		
Gate-Drain Charge	Q_{gd}			1.1		
Gate Resistance	R_g	$f = 1\text{ MHz}$		2.6	3.9	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}$, $R_L = 4.8\text{ }\Omega$ $I_D \cong 3.13\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_G = 1\text{ }\Omega$		4.5	6.75	ns
Rise Time	t_r			11	16.5	
Turn-Off Delay Time	$t_{d(off)}$			12	18	
Fall Time	t_f			7	10.5	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}$, $R_L = 6.25\text{ }\Omega$ $I_D = 2.4\text{ A}$, $V_{GEN} = 4.5\text{ V}$, $R_G = 1\text{ }\Omega$		20	30	ns
			Rise Time	t_r		
Turn-Off Delay Time	$t_{d(off)}$			11	17	
Fall Time	t_f			23	35	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^\circ\text{C}$			1.39	A
Pulse Diode Forward Current ^a	I_{SM}				20	
Body Diode Voltage	V_{SD}	$I_S = 2.0\text{ A}$		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 2.0\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$		10	15	ns
Body Diode Reverse Recovery Charge	Q_{rr}			4	6	nC
Reverse Recovery Fall Time	t_a			6.6		ns
Reverse Recovery Rise Time	t_b			3.5		

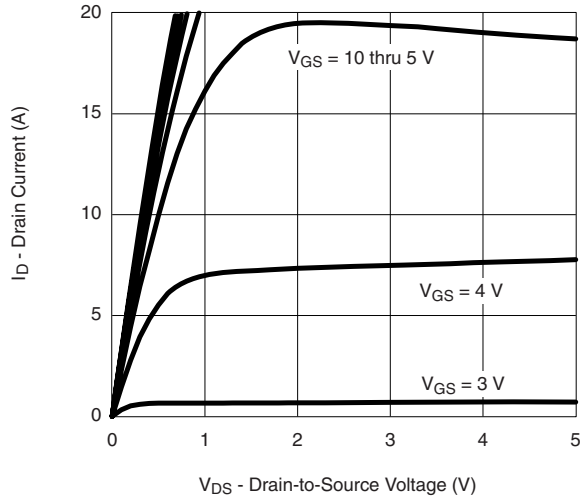
Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

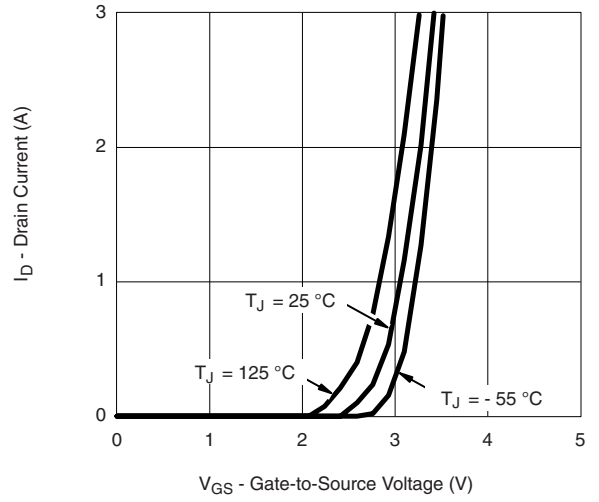
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



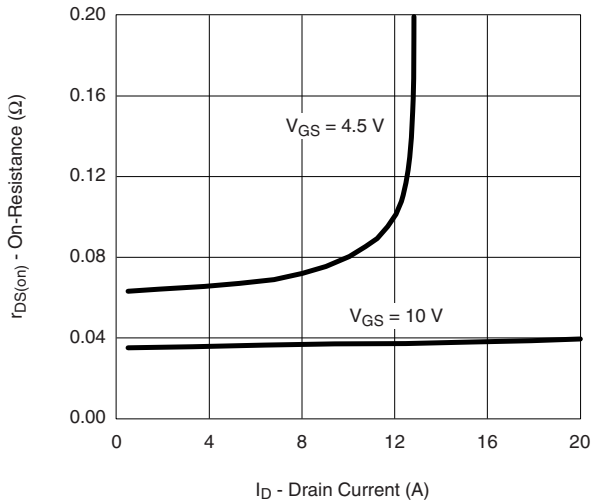
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



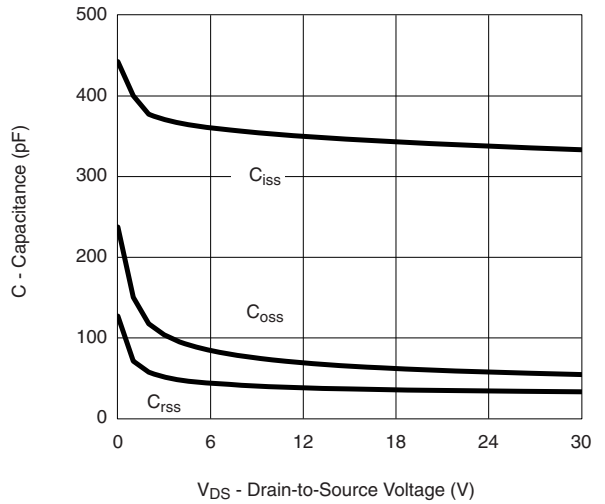
Output Characteristics



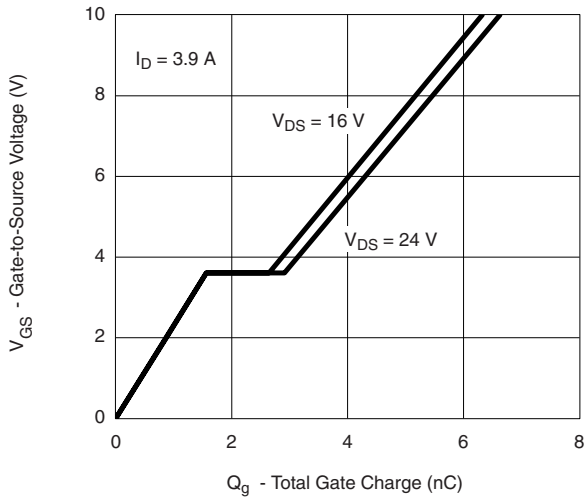
Transfer Characteristics



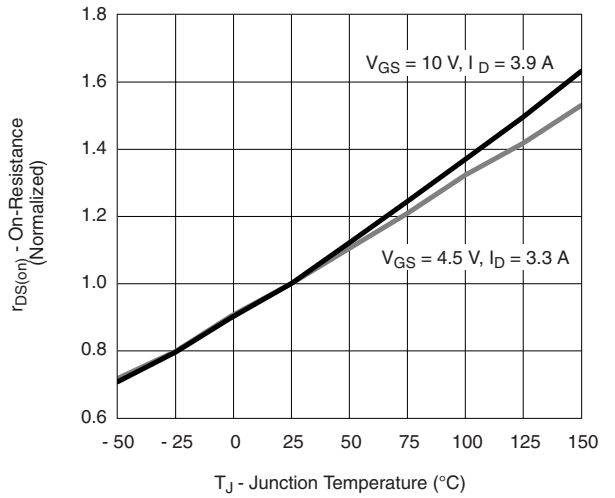
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



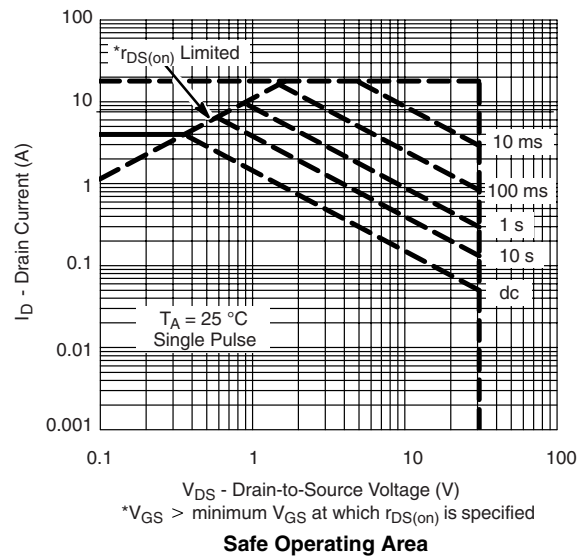
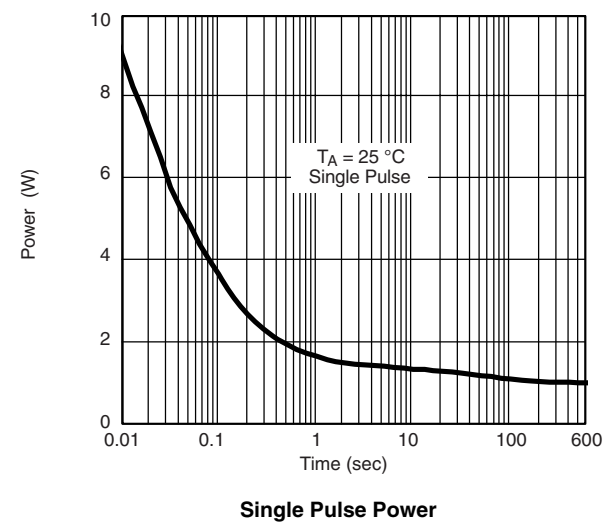
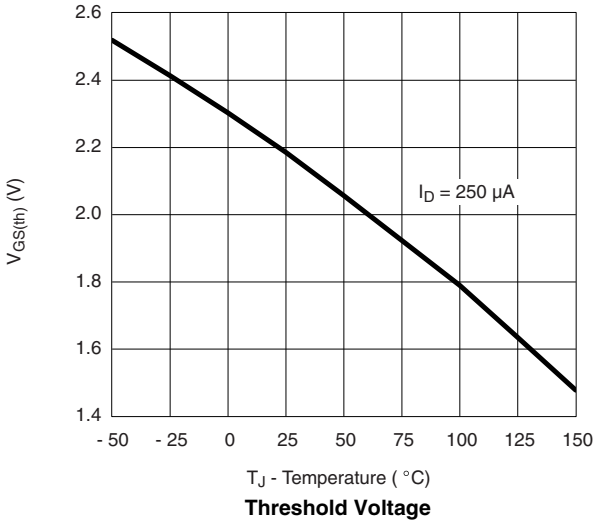
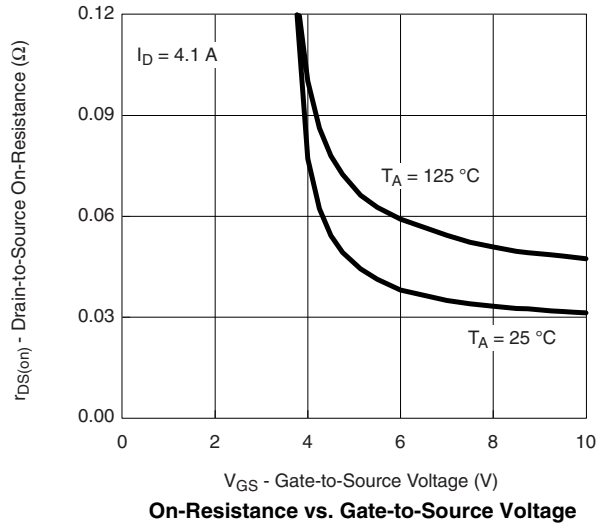
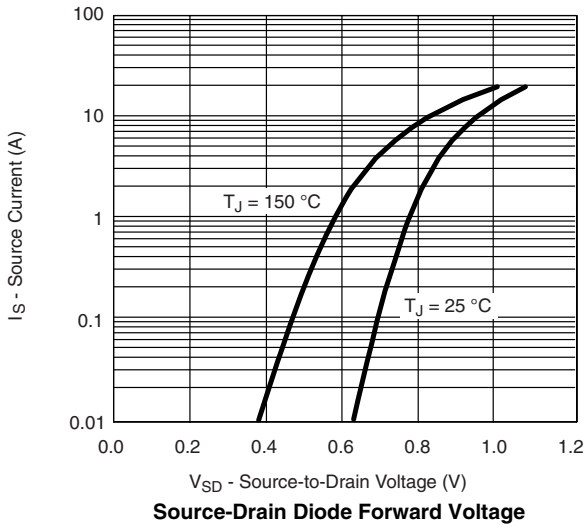
Gate Charge



On-Resistance vs. Junction Temperature

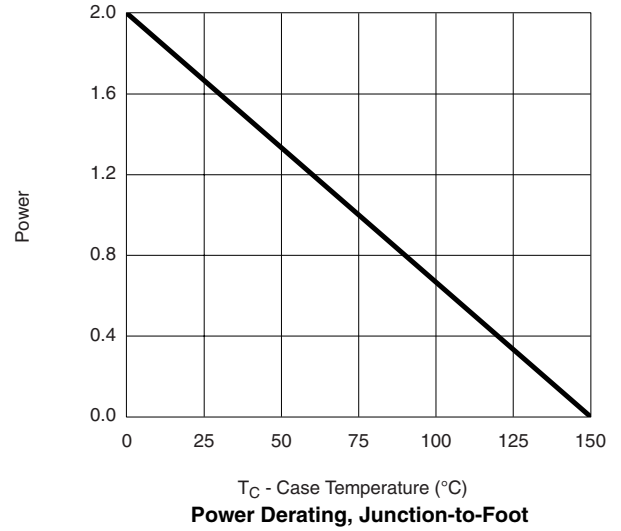
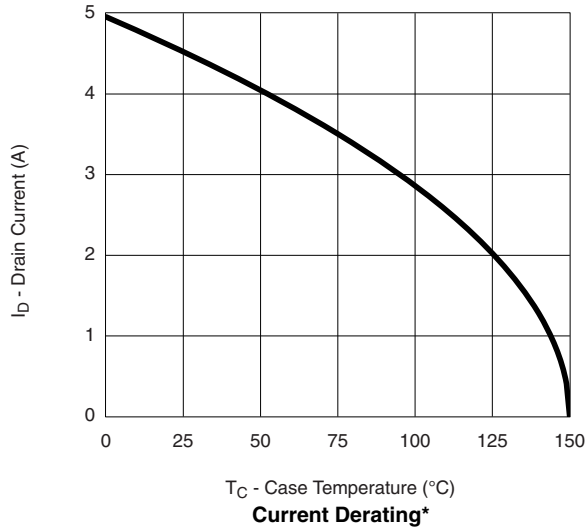


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

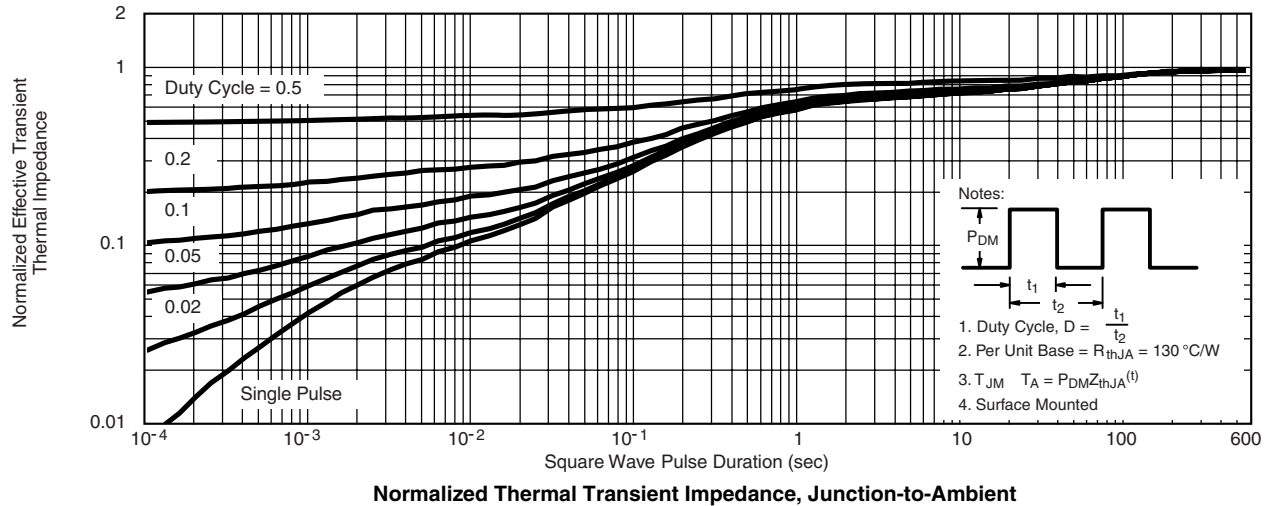




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



*The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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